

ELEC-E9210 Organic Electronics: Materials,
Devices & Applications

Organic Field-Effect Transistors I



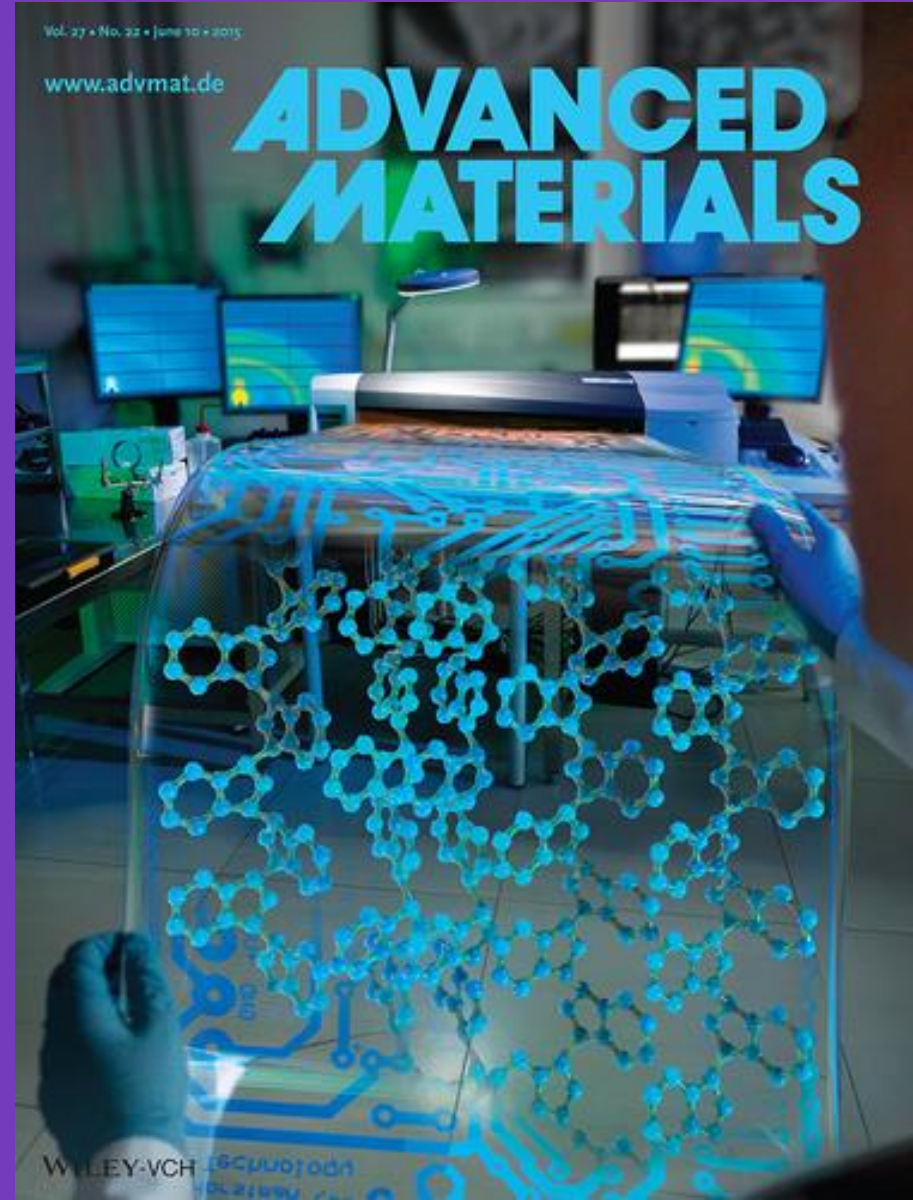
Aalto University
School of Electrical
Engineering

organicelectronics.aalto.fi

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ADVANCED MATERIALS



WILEY-VCH

Today's Class: Organic Field-Effect Transistors

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Previously...

- organic semiconductors electronic properties are strongly affected by **molecular assembly/surface organization** and amount of **disorders** (mobility depends from these parameters)
- excitation in organic materials can lead to **emission of light** (fluorescence, phosphorescence)
- organic materials **morphology** and **packing** are crucial in understanding and engineering **electrical** and **optical** properties

Today

- Basic **working principle** of organic **field-effect transistor** and main features
- **Building blocks** of organic transistor and how to engineer those to improve

Organic Electronics Domains

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Light Emitting Devices



Photodiodes & (Bio)Sensors



Solar Cells

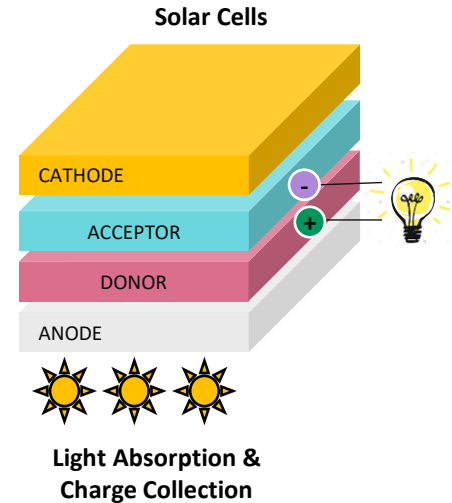
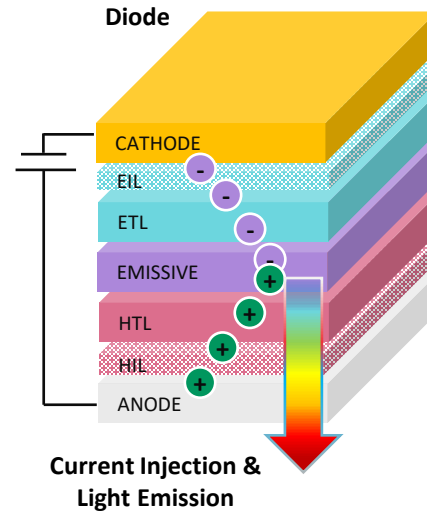
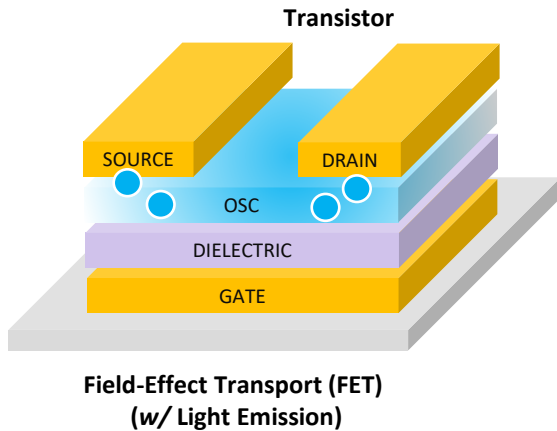


Wearable/Flexible Electronics



Key (Organic) Electronics Devices

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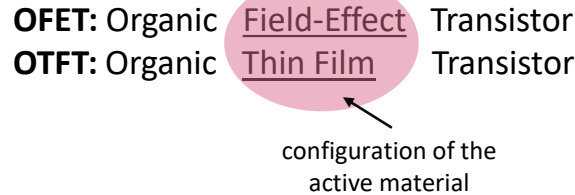


- fundamental mechanisms are similar to inorganic counterparts
- interfaces are crucial for device functioning

Organic (Field-Effect) Transistors

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OFET or OTFT?



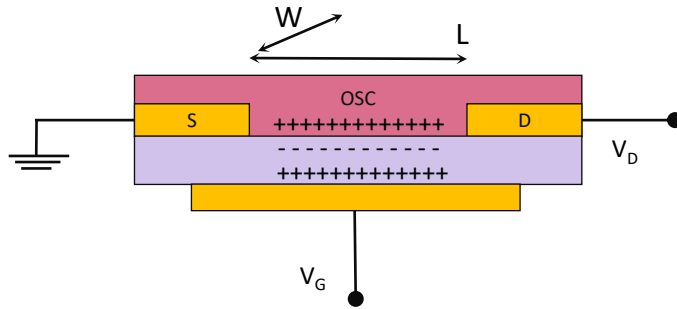
transistor device is based on *field-effect transport*, but there is no strict limitation on the nature of the active materials (*i.e.* thin film, large crystals, ...)

FET: Organic vs. Inorganic

- different structures (lattice vs. orbitals)
- similar concepts but possible different behavior
- transistor:
 - similar fundamental principles
 - fabrication techniques might be different

(Organic) Field-Effect Transistor (OFET)

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- **3 terminals** device (S, D, G)
- **channel length, L** (distance S & D) 10-100s μm
- **channel width, W** (distance between S and D-orthogonal to L (\sim several mm))

Application of gate bias induces polarization at the interface \rightarrow current can flow between source and drain (no traps/Ohmic contact)

capacitance/unit area

$$Q_{mob} = C_i [V_G - V_{th} - V(x)]$$

induced mobile charge at distance x from S

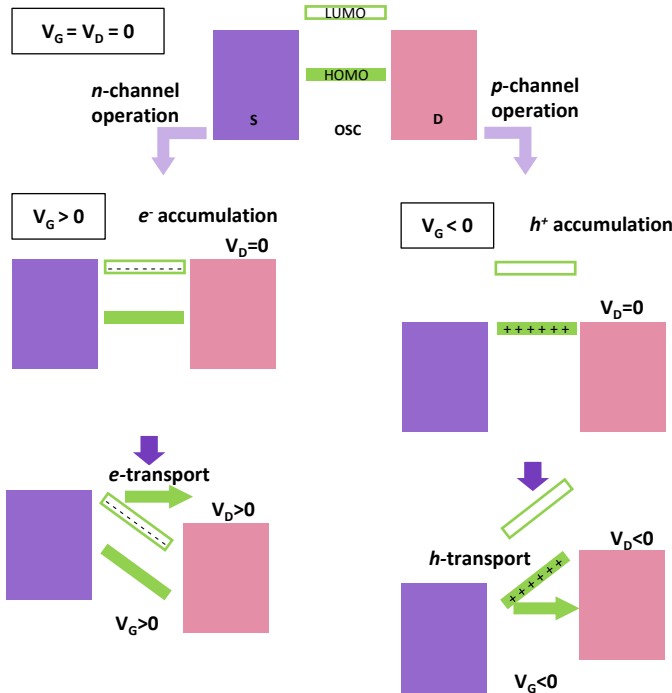
threshold bias at which current starts to flow (device is ON)

$$I_D = W \mu Q_{mob} E_x \quad E_x = dV/dx$$

$$\rightarrow I_D dx = W \mu Q_{mob} dV = W \mu C_i [V_G - V_{th} - V(x)] dV$$

$$I_D = \int_0^L I_D dx = \frac{W}{L} \mu C_i \left[(V_G - V_{th}) V_D - \frac{1}{2} V_D^2 \right]$$

(O)FET: *p*- & *n*- Transport

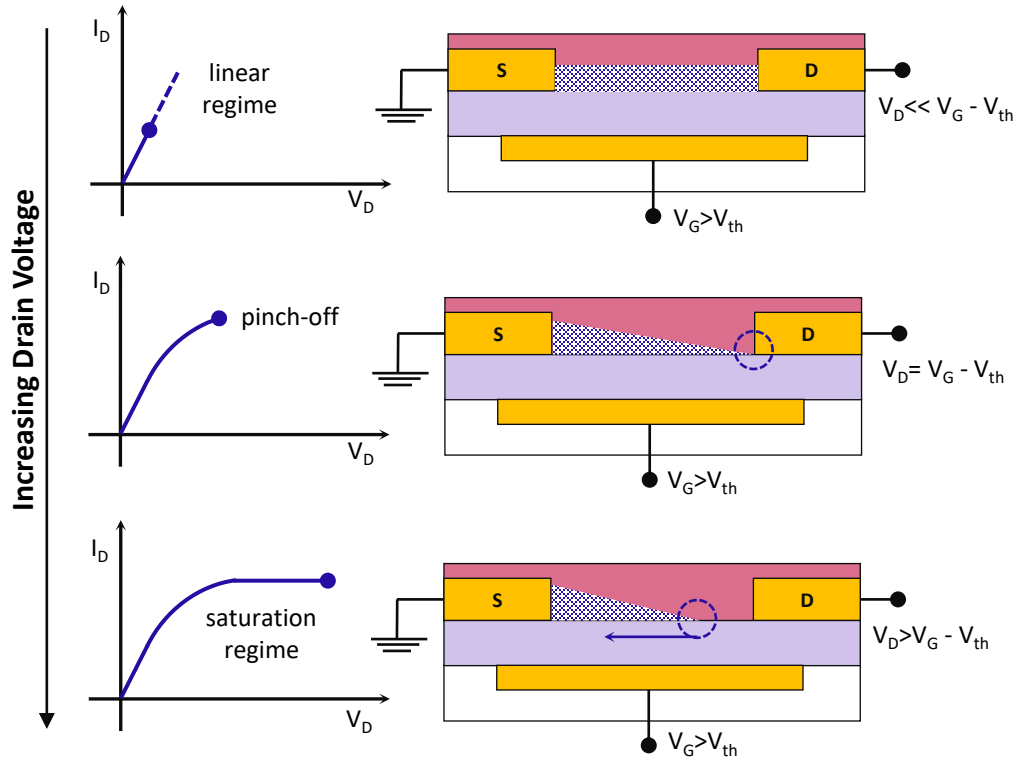


energy level diagram for an transistor in OFF state ($V_G = V_D = 0$)

electric field draws positive charges from the source into a narrow (\leq few nm) region, next to the dielectric
 \rightarrow charges accumulate in the narrow interfacial OSC region

$V_D < 0 \rightarrow$ current starts to flow, however due to OSC traps, these first injected charges will fill the traps
 $V_G > V_{th} \rightarrow$ accumulation layer can actually flow and contribute to the transistor current

(O)FET: Conduction Regimes



charge carrier concentration gradient
(Ohm's law with $Q_{mob} = C_i (V_G - V_{th} - V(x))$)

$$I_{D,lin} = \frac{W}{L} \mu C_i (V_G - V_{th}) V_D$$

mobile charges concentration
reduces to zero at $x = L$ (drain).
Transistor is *pinched off*.

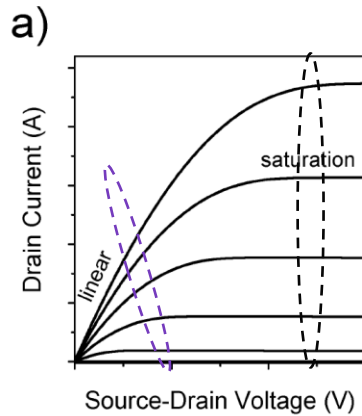
pinch-off point moves towards S, shortening
L and narrowing the depletion zone near D.
Current flows within the channel and
remains constant

$$I_{D,sat} = \frac{W}{2L} \mu C_i (V_G - V_{th})^2$$

(O)FET Characteristic Curves

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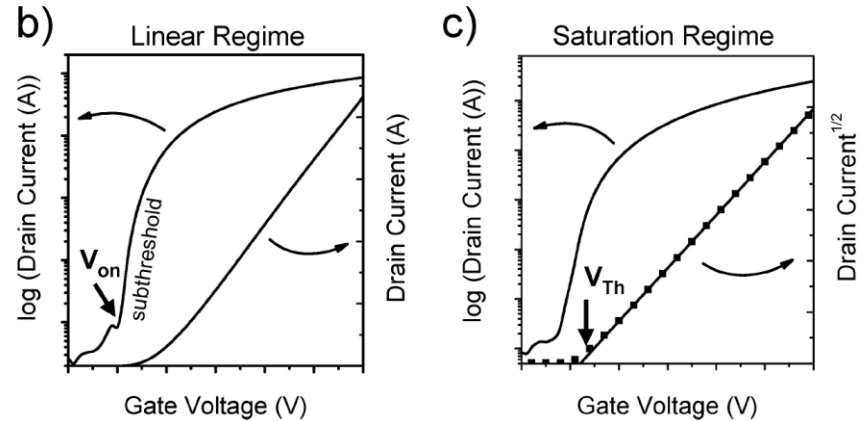
Output Characteristics
(I_D - V_D sweep)



linear: current increases with voltage (Ohm's law)

saturation: current reaches a maximum value prior to leveling with increasing applied voltage

Transfer Characteristics
(I_D - V_G sweep)



subthreshold regime: device is turning from OFF (low-current) to ON (high-current)

high V_G -regime: slope of $I^{1/2}$ can be used to estimate OSC mobility

(O)FET Parameters: Mobility & Threshold

Mobility, μ

charge carriers move accordingly to the direction of the applied electric field (depending on the sign of the charge)



this relation is not linear in the limit of high field and depends on charge carrier concentration

$$v = \mu E \quad [\mu] = [cm^2V^{-1}s^{-1}]$$

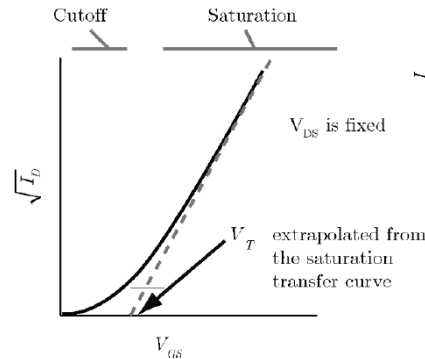
$$\mu = \frac{velocity}{E} = \frac{I_D}{QWE} = \frac{I_D L^2}{C(V_{GS} - V_{th})V_{DS}}$$

$$Q = \frac{C(V_{GS} - V_{th})}{WL}$$

Threshold Voltage, V_{th}

bias for the onset of charge accumulation (bias at which inversion in the channel is achieved)

$$I_D = \frac{W}{2L} \mu C_i (V_G - V_{th})^2$$

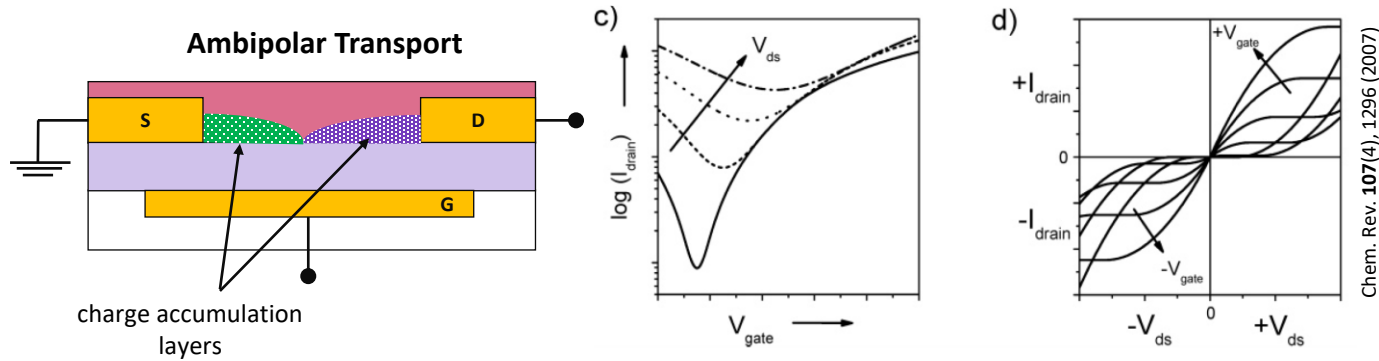


- small currents might flow below V_{th}
- linear/saturation might not closely follow a linear relation
- dependent on choice of linear region

OFET: Ambipolar Behavior

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Due to the nature of the molecular orbitals and defects, an organic semiconductor can **conduct both charge carriers (ambipolar OSC)**

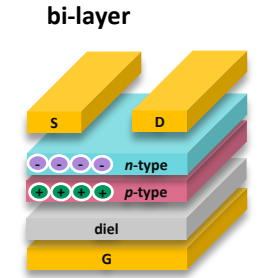


$$|I_{DS}| = \frac{WC_i}{2L} \left\{ \mu_e (V_G - V_{th,e})^2 + \mu_h (V_D - (V_G - V_{th,h}))^2 \right\}$$

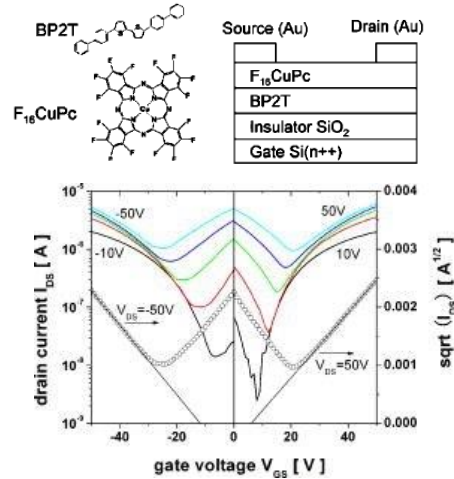
Ambipolar OFET shows an overall behavior which is an **overlap between p- and n-type** charge transport regimes

Ambipolar OFET: Configurations

Ambipolar behavior in transistor can be mainly reached through three approaches:
single ambipolar material, *bi-layer* and *blend* structure

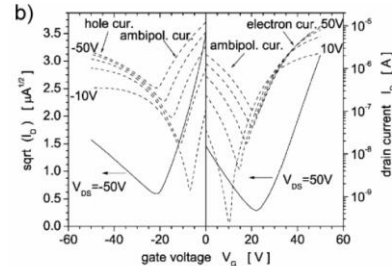
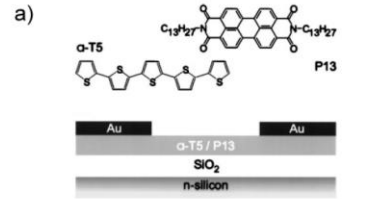


solution-processed bi-layer are challenging to fabricate (solvents compatibility)

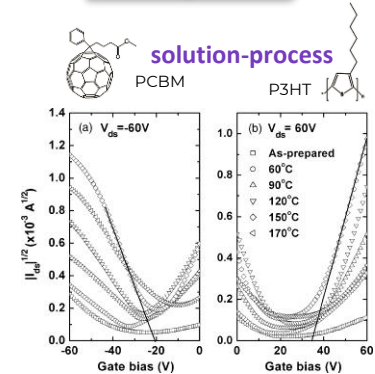
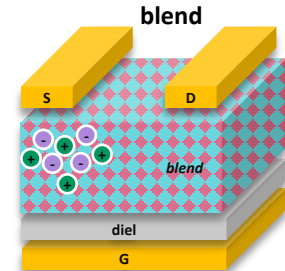


Appl. Phys. Lett. **88**(13), 133508 (2006)

co-evaporation



Appl. Phys. Lett. **85**, 1613 (2004)



J. Appl. Phys. Lett. **89**, 153505 (2006)

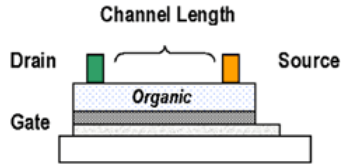
presence of both charges can lead to exciton formation and radiative decay

Vertical OFET (*v*-OFET): A New Concept

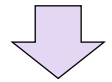
channel length is defined as the **OSC thickness** between (stacked) source and drain
 → nm scale channel length

- by reducing transistor dimension, number of devices in a chip can be (exponentially) increased (Moore's law)
- transistor speed in the 100s GHz range

OFET vs. (V)OFET



- applying $V(G-S)$ → charge density at the OSC/dielectric interface is modulated, switching the device from ON to OFF-state (accumulation → depletion)
- electric field between D and S pulls the charge carriers toward the drain, thus leading to net drain current



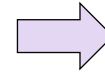
(V)OFET transport is no longer limited to OSC/diel interface but becomes distributed, with contributions in lateral and vertical direction to the gate insulator interface

flexible applications

(bending radius does not affect transistor properties)

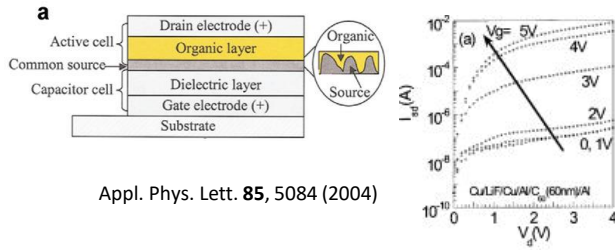
VOFET Structure & Properties

Controlling the barrier if the electric field (G) is not completely screened by the free charge in the S



- electrodes thickness of $\leq 1\text{nm}$
- *discontinuous* source electrode

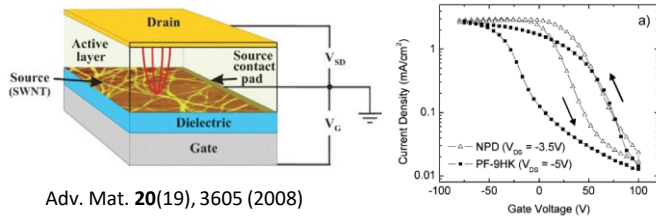
rough metal electrodes



Appl. Phys. Lett. **85**, 5084 (2004)

V-OFET with low working voltage (<5V), high current output (up to 4A/cm²) and high ON/OFF ratio (4×10⁶)

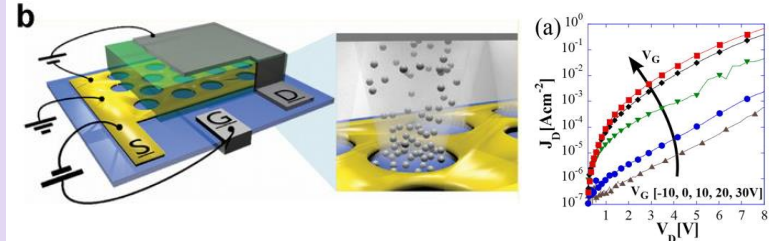
SWNT network



Adv. Mat. **20**(19), 3605 (2008)

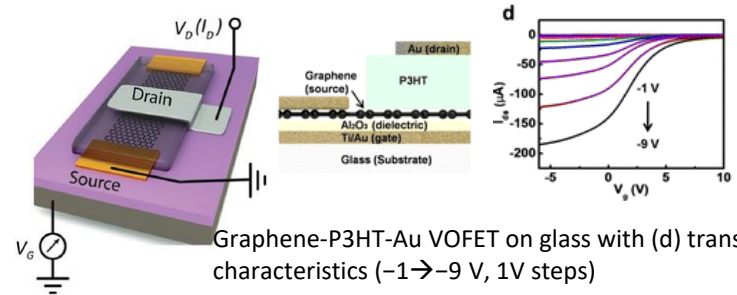
SWNT-network VOFET with transfer characteristics for PF-9HK and NPD-based device

(nano)patterned electrode



V-OFET exhibits *n*-type ON/OFF ratio >10³, current density >50mA/cm² @V_{DS} = 5 V, as well as *p*-type operation

graphene



Graphene-P3HT-Au VOFET on glass with (d) transfer characteristics (-1→-9 V, 1V steps)

Summary

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Today's Class

- Basic *working principle* of organic field-effect transistor and some characteristics

Next

- *Building blocks* of organic field-effect transistor
- *Applications* of organic field-effect transistors

